### T-1 (3mm) RIGHT ANGLE LED INDICATOR

Part Number: WP934GF/GT

Green

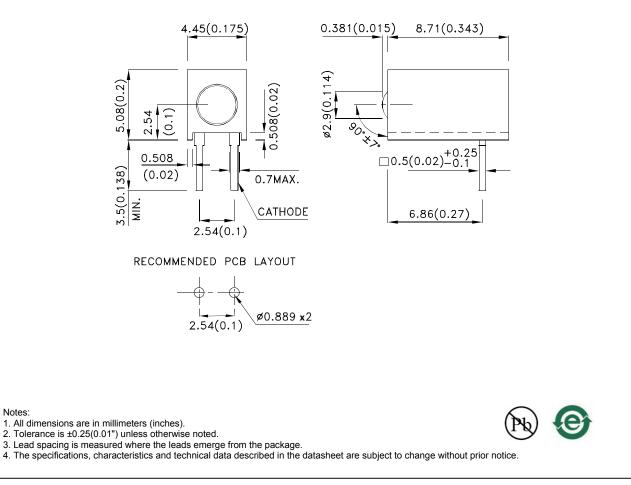
#### Features

- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating: 94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

#### Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

#### **Package Dimensions**



REV NO: V.4B CHECKED: Allen Liu DATE: FEB/15/2016 DRAWN: L.Q.Xie PAGE: 1 OF 5 ERP: 1102013243

#### **Selection Guide** Viewing lv (mcd) [2] @ 10mA Angle [1] Part No. **Emitting Color (Material)** Lens Type Min. 201/2 Тур. WP934GF/GT Green (GaP) 40 34° Green Transparent 12

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous Flux: +/-15%

3. Luminous intensity value is traceable to CIE127-2007 standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	565		nm	IF=10mA
λD [1]	Dominant Wavelength	Green	568		nm	IF=10mA
Δλ1/2	Spectral Line Half-width	Green	30		nm	IF=10mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2	2.5	V	I⊧=10mA
IR	Reverse Current	Green		10	uA	VR = 5V

Notes:

1. Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

#### Absolute Maximum Ratings at TA=25°C

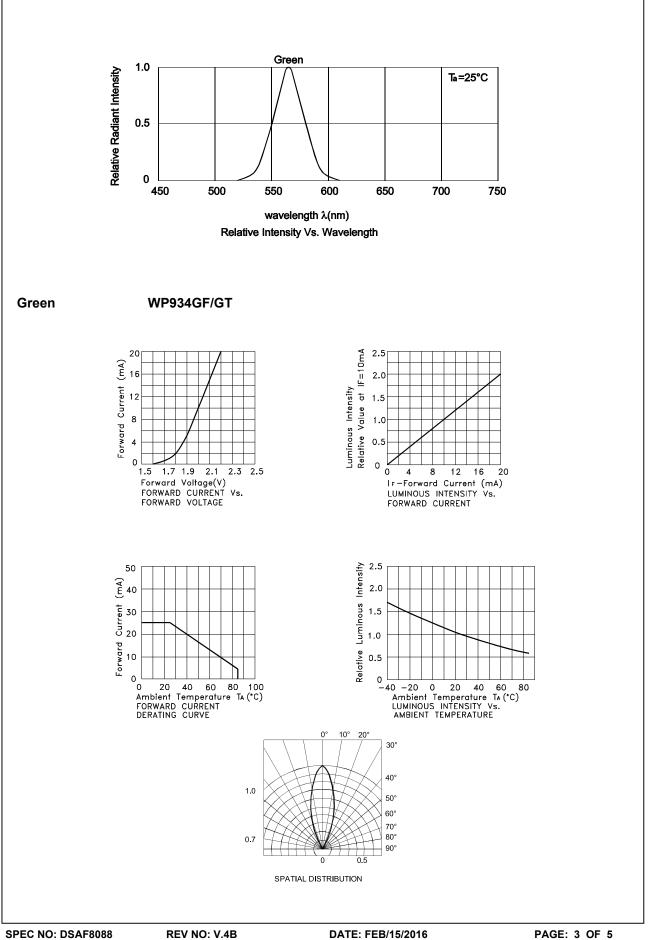
Parameter	Values	Units		
Power dissipation	62.5	mW		
DC Forward Current	25	mA		
Peak Forward Current [1]	140	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

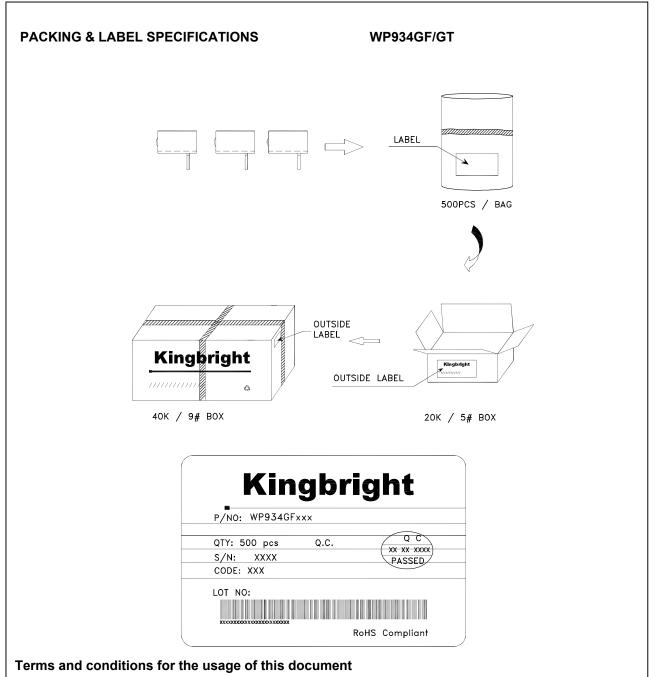
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

Smm below package base.
Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.





- 1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- 4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
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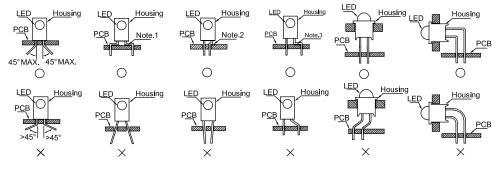
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#### PRECAUTIONS

1. Storage conditions:

a.Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.

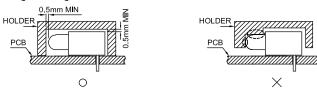
- b.LEDs should be stored with temperature  $\leq 30^{\circ}$  C and relative humidity < 60%.
- c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



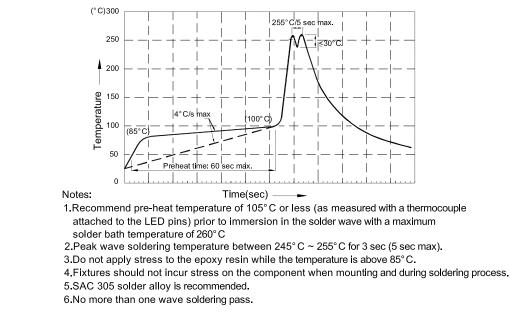
" ( ) " Correct mounting method " imes " Incorrect mounting method

Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 4. The tip of the soldering iron should never touch the lens epoxy.
- 5. Through-hole LEDs are incompatible with reflow soldering.
- 6. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 7. Recommended Wave Soldering Profiles:



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